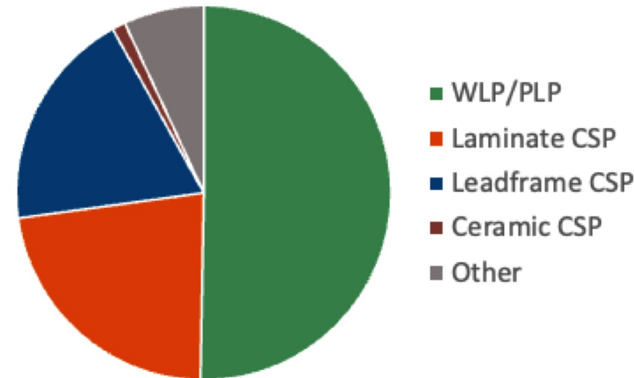
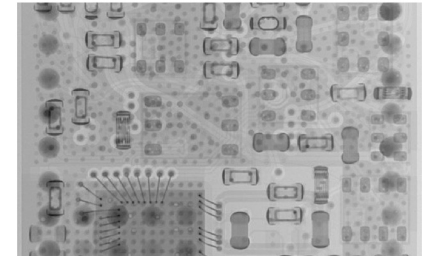
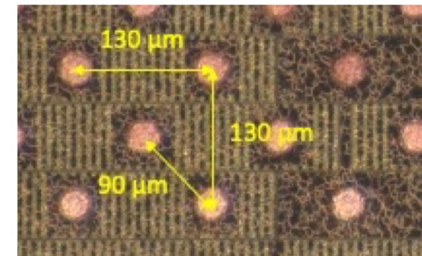
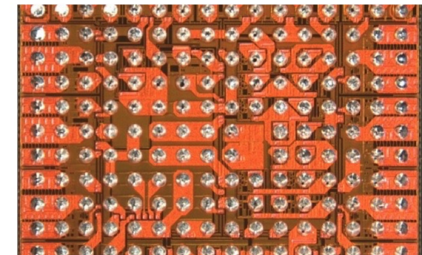
Google Pixel 8 Pro

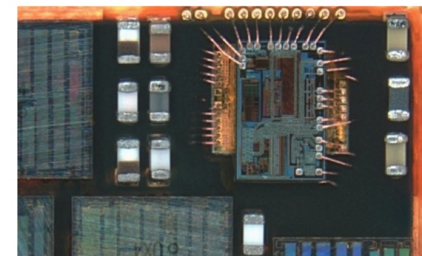
Teardown from TechSearch International, Inc.

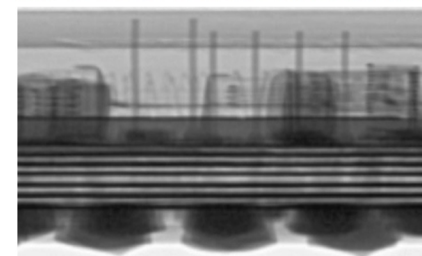












Contents and Highlights

- 191-page report with package summaries, high-resolution photographs and x-rays, package dimensions, thermal management material analysis
- 25 slides with extra details including package construction analysis and die characteristics of Google Tensor G3 processor co-designed by Samsung and Google and assembled with Samsung's panel fan-out technology, decapsulation of USI's highly-integrated Wi-Fi 7/Bluetooth 5.2 module, decapsulation of Qorvo's QM35725 UWB transceiver module, analysis of RF FEMs with conformal and compartmental shielding, characteristics of Samsung's 50MP ISOCELL GNK image sensor, and decapsulation of Melexis MLX90632 IR temperature sensor
- Pixel 8 Pro has 7% more packages than the Pixel 7 Pro, which had a total of 161

Teardowns backed by 36 years serving as the industry's trusted source for semiconductor packaging trend analysis

- Examination of all chips with emphasis on assembly and packaging technologies
- Superb quality photographs and x-ray images
- Both the packages and the die within are identified and characterized
- Detailed construction analysis of key chips and packages

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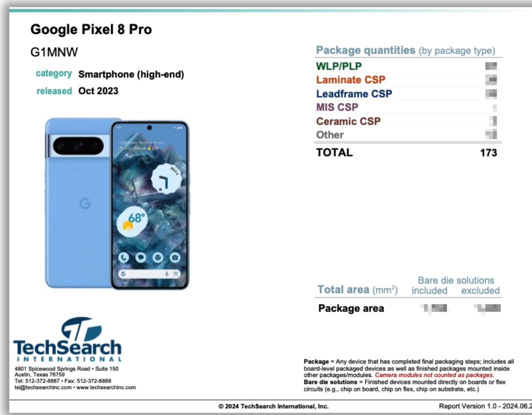
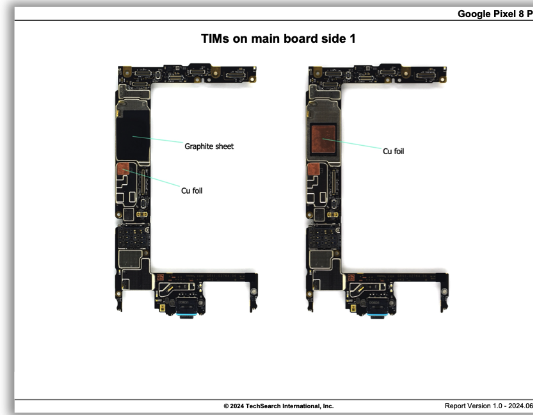
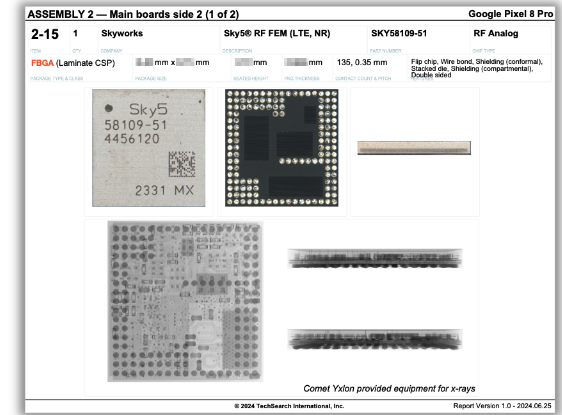
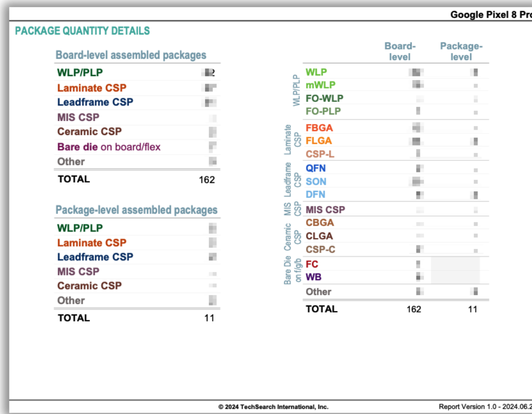
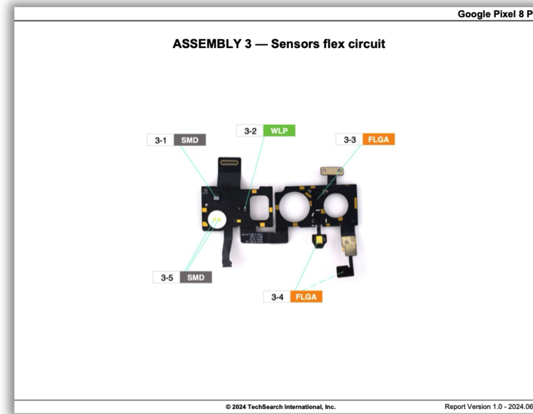
Sample pages from the report and slides

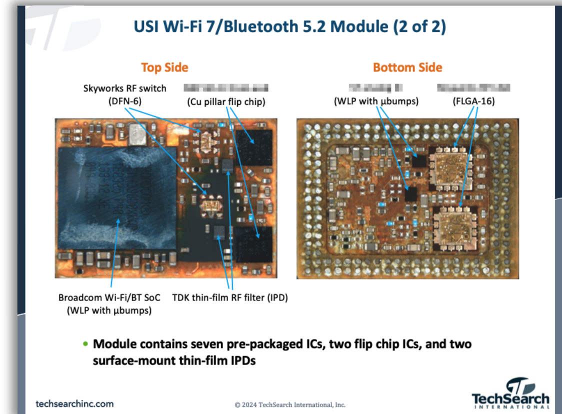


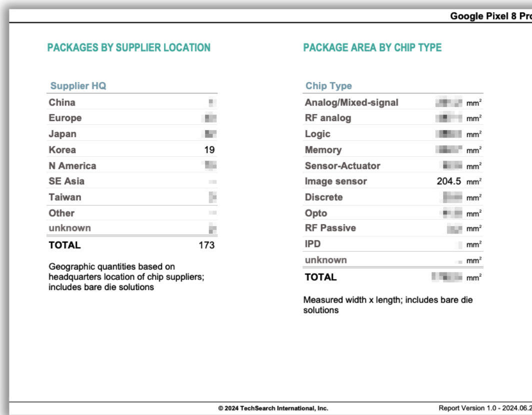


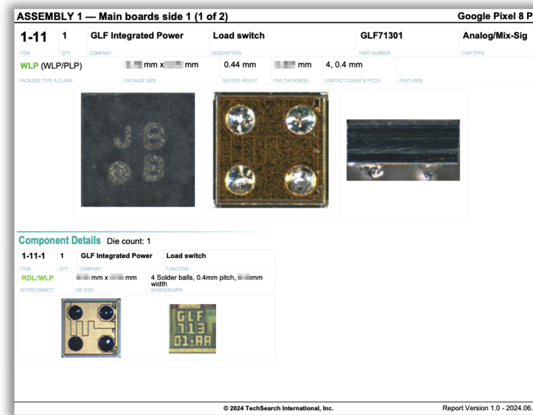


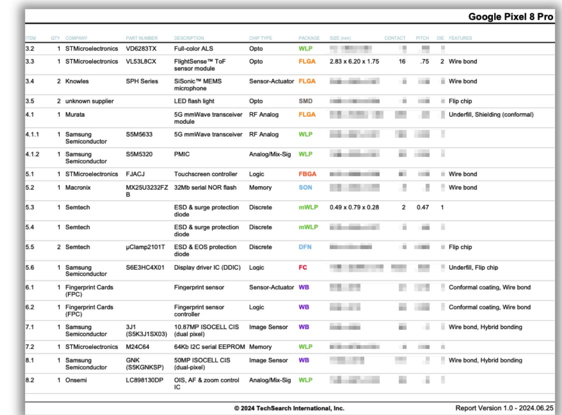












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